

WHAT IS CLAIMED IS:

1. A semiconductor integrated circuit device having bumps, which are used for electrically connecting by face down bonding and provided in a terminal section on a surface of a semiconductor substrate thereof, said semiconductor integrated circuit device further comprising:
- 5 facedown bonding dummy bumps which are connected non-electrically and disposed in a vicinity of one or more corner sections of four corners of a semiconductor chip, wherein an area of each of said facedown bonding dummy bumps projected onto a chip is larger than that of the area of each said facedown bonding bumps.
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2. The semiconductor integrated circuit device according to claim 1, wherein said dummy bumps are functioning as shock absorbing members for alleviating load stress due to the facedown bonding, and are not electrically connected to a wiring of which part is disposed to be overlapped to said facedown bonding dummy bumps with at least one insulating film being interposed in-between.
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